

In the Claims

Kindly amend the claims as shown. Claims remaining in the application are as follows:

1. (Currently Amended): A printed circuit assembly carrier comprising:
a carrier frame configured to hold a one printed circuit assembly ~~of selected from~~ at least two different printed circuit assembly types that respectively mount to a storage drive in at least two different orientations with respect to the storage drive;
a first toolless retention feature coupled to a first surface of the carrier frame and configured to retain the selected one printed circuit assembly ~~of a first printed circuit assembly type in a first orientation to the carrier frame~~; and
a second toolless retention feature coupled to a second surface of the carrier frame and configured to retain the carrier frame to the storage drive, printed circuit assembly of a second printed circuit assembly type in a second configuration that is different from the first orientation the first and second toolless retention features being mutually configured to hold the at least two different printed circuit assembly types in respective different orientations with respect to the storage drive.
2. (Previously presented): The carrier according to Claim 1 wherein:
the carrier frame and first and second toolless retention features are constructed from molded plastic and configured to selectively support one of two different printed circuit assemblies that install in two different orientations.
3. (Currently Amended): The carrier according to Claim 1 wherein:
the carrier frame comprises a first member having parallel opposing planar surfaces including an interior planar surface and an exterior planar surface, the ~~exterior~~ interior planar surface being the first surface coupled to the first toolless retention feature, the ~~interior~~ exterior planar surface being configured to receive and retain the printed circuit assembly the second surface coupled to the second toolless retention feature.

4. (Original): The carrier according to Claim 3 wherein:

the carrier frame comprises a second member coupled at an end of the first member substantially perpendicular to the first member, the second member extending beyond the interior planar surface to the second surface that couples to the second toolless retention feature.

5. (Currently Amended): The carrier according to Claim 1 further comprising: mounting features coupled to the carrier frame adapted to mount a the selected one printed circuit assembly of the at least two different printed circuit assembly types, whereby the at least two different printed circuit assembly types mount to the same features.

6. (Original): The carrier according to Claim 1 further comprising: a cable retention feature coupled to the carrier frame.

7. (Currently Amended): An electronic device assembly comprising:
a housing;
first and second printed circuit assemblies of respective different first and second types adapted to couple to the housing;
first and second identical printed circuit assembly carriers adapted to respectively couple the first and second printed circuit assemblies to the housing, the carriers coupling the printed circuit assemblies of different types to the housing in different orientations with respect to the housing via toolless retention features.

8. (Previously presented): The electronic device assembly according to Claim 7 further comprising:
a third printed circuit assembly configured to couple to a side of the housing.

9. (Previously presented): The electronic device assembly according to Claim 7 further comprising:
a third printed circuit assembly configured to couple to a side of the housing, the third printed circuit assembly being substantially planar and having a first

planar side configured to couple to the housing and a second opposing planar side, wherein
the first identical printed circuit assembly carrier coupling the first printed circuit assembly to the second planar side of the third printed circuit assembly.

10. (Previously presented): The electronic device assembly according to Claim 7 further comprising:

a third printed circuit assembly adapted to couple to a side of the housing, the third printed circuit assembly being substantially planar and having a first planar side adapted to couple to the housing and a second opposing planar side, wherein

the second identical printed circuit assembly carrier coupling the second printed circuit assembly substantially perpendicular to the third printed circuit assembly.

11. (Previously presented): The electronic device assembly according to Claim 10 wherein:

the second printed circuit assembly and the second identical printed circuit assembly carrier are implemented for usage of the electronic device assembly in a duplex configuration.

12. (Previously presented): The electronic device assembly according to Claim 7 further comprising:

a third printed circuit assembly adapted to couple to a side of the housing, wherein:
the electronic device is a hard disk drive;

the housing is a hard disk drive housing, chassis, or cage; and

the first printed circuit assembly is a management printed circuit assembly, the second printed circuit assembly is a duplex printed circuit assembly, and the third printed circuit assembly is a hard disk drive printed circuit assembly.

13. (Original): The electronic device assembly according to Claim 7 further comprising:

a cable retention feature coupled to the carriers.

14-28. (Canceled)

29. (New): The carrier according to Claim 1 wherein:
the storage drive is at least one hard disk drive and the carrier frame is
configured to hold the at least two different printed circuit assembly types in
modes selected from a simplex mode and a duplex mode.

30. (New): The assembly according to Claim 7 further comprising:
the first and second identical printed circuit assembly carriers configured to secure
first and second different printed circuit assembly types;
mounting features coupled to the first and second identical printed circuit assembly
carriers configured to mount the first and second different printed circuit
assembly types; and
a plurality of toolless retention features coupled to the first and second identical
printed circuit assembly carriers and configured to retain the mounted first
and second different printed circuit assembly types to the electronic device in
respective different orientations.

31. (New): The assembly according to Claim 7 further comprising:
a hard disk drive;
a hard disk drive housing containing the hard disk drive;
a hard disk drive printed circuit assembly coupled to the hard disk drive housing;
a manageability printed circuit assembly; and
the first printed circuit assembly carrier coupling the manageability printed circuit
assembly to the hard disk drive printed circuit assembly in a first orientation.

32. (New): The assembly according to Claim 7 further comprising:
a duplex printed circuit assembly; and
the second printed circuit assembly carrier coupling the duplex printed circuit
assembly to the hard disk drive housing in a second orientation.

33. (New): The assembly according to Claim 7 further comprising:
a hard disk drive;
a hard disk drive housing containing the hard disk drive;

a planar hard disk drive printed circuit assembly having a front side and a rear side,
the front side being coupled to the hard disk drive housing;
a manageability printed circuit assembly; and
the first printed circuit assembly carrier coupling the manageability printed circuit
assembly to the rear side of the hard disk drive printed circuit assembly in a
first orientation parallel to the hard disk drive printed circuit assembly.

34. (New): The assembly according to Claim 33 further comprising:
a duplex printed circuit assembly; and
the second printed circuit assembly carrier coupling the duplex printed circuit
assembly to the hard disk drive housing in a second orientation perpendicular
to the hard disk drive printed circuit assembly front side whereby the duplex
printed circuit assembly attaches to the hard disk drive printed circuit
assembly front side.

35. (New): The assembly according to Claim 34 wherein:
the second printed circuit assembly carrier couples the duplex printed circuit
assembly to the hard disk drive housing in physical separation from the hard
disk drive housing wherein physical contact is prevented.